CHIPQUIK®

SMDSWLF.059 3.3 1LB

Datasheet revision 1.2 <u>www.chipquik.com</u>

Solder Wire SAC305 No-Clean 0.059" (1.5mm) with 3.3% Flux Core 1lb Spool

Product Highlights

No-Clean Water-Washable Synthetic Flux Core

The clear, non-corrosive, non-conductive residue is meant to be left on the board. Residues that do remain are water soluble if you want to remove them. Clean with hot water at 60°C (140°F) minimum.

3.3% flux core

Halogen content: None

RoHS 3 and REACH compliant

Specifications

Alloy: Sn96.5/Ag3.0/Cu0.5 Wire Diameter: 0.059" (1.5mm)

Flux Type: No-Clean Water-Washable Synthetic

Flux Classification: REL0

Melting Point: 217-220°C (423-428°F)

Packaging: 1 lb spool Shelf Life: >60 months

Test Results

Test J-STD-004 or other	Test Requirement	Result
requirements as stated		
Copper Mirror	IPC-TM-650: 2.3.32	L: No breakthrough
Corrosion	IPC-TM-650: 2.6.15	L: No corrosion
Quantitative Halides	IPC-TM-650: 2.3.28.1	L: <0.05%
Electrochemical Migration	IPC-TM-650: 2.6.14.1	L: <1 decade drop (No-clean)
Surface Insulation Resistance 85°C,	IPC-TM-650: 2.6.3.7	L: ≥100MΩ (No-clean)
85% RH @ 168 Hours		
Visual	IPC-TM-650: 3.4.2.5	Clear and free from precipitation
Conflict Minerals Compliance	Electronic Industry Citizenship	Compliant
•	Coalition (EICC)	
REACH Compliance	Articles 33 and 67 of Regulation (EC)	Contains no substance >0.1% w/w that
	No 1907/2006	is listed as a SVHC or restricted for
		use in solder materials

Conforms to the following Industry Standards:

J-STD-004B, Amendment 1 (Solder Fluxes):	Yes
J-STD-006C, Amendments 1 & 2 (Solder Alloys and Fluxed/Non-Fluxed Solders):	Yes
RoHS 3 Directive (EU) 2015/863:	Yes